



Material Composition Declaration

Package Information

Package	Package Weight (mg)	Terminal Finish	MSL Rating
SOT-363	6	Matte Tin (Sn)	1

Product Group

Type No.	Description
RB731XN	Diode Schottky 30mA 40V
SD103ATW	Diode Schottky 175mA 40V
BAT54ADW / CDW / SDW	Diode Schottky 200mA 30V
BAT54BRW, BAT54TW	Diode Schottky 200mA 30V
BAS16TW, BAV70DW, BAV99BRW, BAV756DW	Diode Switching 150mA 75V
BAW56DW, BAW567DW, MMBD4148TW	Diode Switching 150mA 75V
BAV99DW	Diode Switching 215mA 75V
BAV199DW	Diode Switching 215mA 85V
MMBD4448DW	Diode Switching 250mA 75V
MMBD4448HADW / HCDW / HSDW	Diode Switching 250mA 80V
MMBD4448HAQW / HCQW	Diode Switching 250mA 80V
MMBD4448HTW	Diode Switching 250mA 80V

Component	Material	Substance	CAS No.	Material Mass (%)	Material Mass (mg)	Component Mass (%)	Component Mass (mg)	PPM
Die	Doped Silicon*	Si	7440-21-3	100.00	0.184	3.07	0.184	30667
Wire Bond	Gold	Au	7440-57-5	100.00	0.019	0.32	0.019	3167
Leadframe	Ferrous Alloy	Fe	7439-89-6	56.40	1.337	39.52	2.371	222874
		Ni	7440-02-0	42.00	0.996			165970
		Mn	7439-96-5	0.80	0.019			3161
		Co	7440-48-4	0.50	0.012			1976
		Si	7440-21-3	0.30	0.007			1186
Die Bond	Silver Silicone	Ag	7440-22-4	80.00	0.053	1.10	0.066	8800
		Bisphenol F	28064-14-4	15.00	0.010			1650
		Glycidyl neodeconate	26761-45-5	5.00	0.003			550
Plating	Matte Tin	Sn	7440-31-5	100.00	0.194	3.23	0.194	32333
Encapsulation	EMC	Silica	7631-86-9	79.00	2.501	52.76	3.166	416857
		Epoxy Resin	29690-82-2	20.00	0.633			105533
		Carbon Black	1333-86-4	1.00	0.032			5277

Tolerance ±10%

*Dopant and metallization of the silicon die are not reported in this statement where their concentration is less than the minimum reportable level per EIA JIG-101.

Data disclosed herewith is approximate and is based on information from suppliers surveys, Material Safety Datasheet, engineering calculations and measurements. Won-Top Electronics(WTE) has checked all information carefully and believes it to be correct and accurate. However, WTE cannot assume any responsibility for inaccuracies. WTE reserves the right to change any or all information herein without further notice.

RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronics Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBD) to 0.1%(1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01%(100 PPM) in homogeneous materials of electronics products.

The product group listed above and the homogenous materials are compliant with the Directive 2011/65/EU. WTE warrants that all its packing, components and/or products supplied to the Customer and/or its affiliated companies or designated contractors do not contain these hazardous substances in quantity levels higher than or equal to the thresholds to this directive.

Exemptions as declared for the directive are:

- 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
- 7(c)-I Lead in glass (applicable for glass passivated silicon die).